

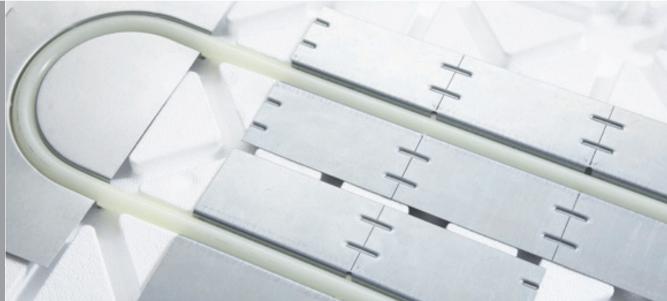


DRY FLOORING BOARDS WITH CONDUCTIVE STRIPS









DEO = Ground level application beneath screed and without footfall sound protection ABZ = standard construction technology DiBT approved = German Industry for Building Regulations		1/2	
	TBS ND 25	TBS Heat conduction	TBS Heat conduction strip
Description	Dry wall element	TBS Heat conduction 750	TBS Heat conduction strip 180°
Item no.	1920218	1920219	1920220
Pipe diameter in mm	14 mm		
Scope of application as per DIN 4108-10	DEO ds, WAB		
Model as per EN 13163	EPS 200		
EN 13163	EPS-EN 13163-T1-L1-W1-S1-P3- DS(70,-)3-DS(N)5 BS250-DLT(1)5- CS(10)200		
Thermal conductivity DIN V 4108-10 in W/mK	0.035		
RD-value (thermal resistance)	0,56 m² K / W		
Compressive stress	200 kPa		
CS (10) max. Usable	60 kPa		
area per board	0.625 m²		
Immediate spacing distance	125 mm		
EPS board dimensions in mm	1020 x 645 x 25		
mm Overall board area	25 mm		
Cardboard (L x W x H) in mm	1030 x 655 x 560 mm		
VPE per unit/carton	21	50	25
VPE carton/pallet	8	27	60
Usable pallet area	105.04 m²		
Dimensions in mm		750 x 120 mm	245 x 125.5 mm
Material thickness		0.5 mm	0.5 mm
in mm			
Material		Galvanised sheet steel	Galvanised sheet steel

Specific features:

- allows for adjustments to floor, wall and drywall temperatures
- a low static weight for instance allows you to also make use of this item in old listed building and in loft conversions
- It is possible to weave, meander and install diagonally
- simple installation with one basic element (zero edge areas or head units are required)
- rapid and clean installation is possible thanks to pre-positioned pipe channels
- allows for quick arrangements and supreme comfort
- can be adjusted to any type of floor plan
- optimal heat distribution thanks to thermal slats even in the arc region
- thermal slat processing which require zero tools, and which can be bridged by snapping off at intervals of 100 mm
- 25 mm is very low, which allows for a minimal total construction height of 45 mm of (and works with special screed elements including floor or wall related processes)